



Cascadable Silicon Bipolar MMIC Amplifier

Description

The PHA-0670B is a high performance silicon bipolar Monolithic Microwave Integrated Circuit (MMIC) housed in a hermetic high reliability 70 mil microstrip package. This MMIC is designed for use as a general purpose 50 Ω gain block. Typical applications include narrow and broad band IF and RF amplifiers in industrial and military applications.

VO U is not the original device manufacturer. TMS procures commercial off the shelf product and UpScreens per the following process flow. For custom screening requirements, Quality Conformance Inspection, or additional electrical selection, please contact TMS.

Technical Data

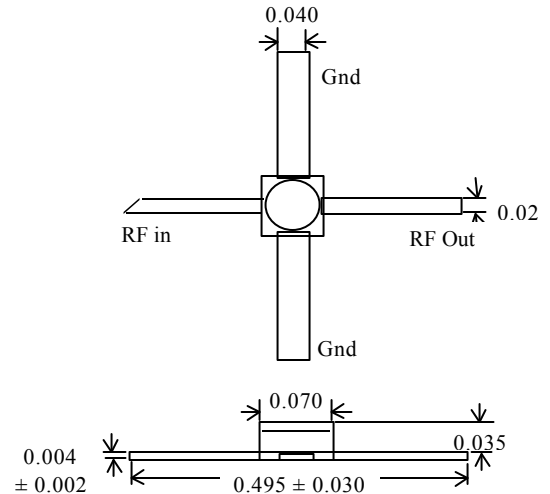
PHA-0670B Suggested Maximum Ratings

Parameter	Suggested Maximum ^[1]
Device Current	50 mA
RF Input Power	+13 dBm
Junction Temperature	+200°C
Storage Temperature	-65 to +200°C

NOTE:

1. Permanent damage may occur if any of these limits are exceeded.

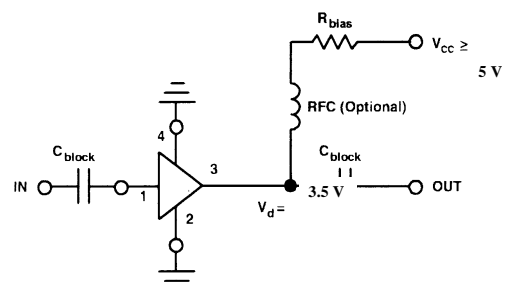
70 mil Package Dimensions



NOTES: (Unless otherwise specified)

1. Dimensions are in inches
2. Tolerances: X.XXX = ±0.005

Typical Biasing Configuration



Electrical Specifications [1]			-55°C		+25°C		+125°C	
Symbol	Parameters and Test Conditions	Units	Min	Max	Min	Max	Min	Max
G_p	Power Gain ($ S_{21} ^2$) f=0.1 GHz	dB	16.5	24.5	18.5	22.5	16.5	24.5
ΔG_p	Gain Flatness f=0.1 to 0.6 GHz	dB		± 1.6		± 1.2		± 1.6
V_d	Device Voltage @ 16 mA	V	2.0	5.0	3.1	4.0	2.0	5.0

NOTE:

1. The recommended operating current range for this device is 12 to 30 mA.

TMS UpScreen

Table 2A 100% Screening

Screening Test/Operation	MIL-STD-883 Method	Conditions
Stabilization Bake	1008	Condition C, Ta = +150 °C t= 24 hrs.
Temperature Cycling	1010	Condition C, -65 to +150°C, 10 cycles minimum
Constant Acceleration	2001	Condition E, 30,000 G, Y1 axis only
Pre Burn-in Electrical Test (optional)		+25°C; Gp, ΔGp, and Vd
Burn-in	1015	Condition B, t= 160 hrs., Ta= +125°C
Final Electrical Test	-----	+25°C; Gp, ΔGp, and Vd
Percent Defective Allowable (PDA)		5% max.; applies to 25°C Final Electrical Test
Hermeticity		
Fine Leak	1014	Condition A
Gross Leak	1014	Condition C
External Visual	2009	
Group A Inspection		n = 116, r = 1
+125°C		Gp, Vd and ΔGp
-55 °C		Gp, Vd and ΔGp
Shipment Packaging		10 units per strip

Marking: Manufacturer's marking (if applicable) will remain on devices. TMS individual packaging will be labeled with TMS Part Number and manufacturer date code. TMS shipment date code will appear on outer label and C of C. Certificate of Conformance (C of C) will be sent with each shipment. This document provides objective evidence of TMS testing and documents traceability to manufacturers wafer/lot identification.